Abstracts

Millimeterwave characteristics of flip-chip interconnects for multi-chip modules

W. Heinrich, A. Jentzsch and G. Baumann. "Millimeterwave characteristics of flip-chip interconnects for multi-chip modules." 1998 MTT-S International Microwave Symposium Digest 98.2 (1998 Vol. II [MWSYM]): 1083-1086.

Electromagnetic simulations and measurement data of flip-chip transitions are presented. First-order effects are identified and design criteria for mm-wave multi-chip interconnects are derived. In coplanar environment, the flip-chip scheme provides interconnects with excellent low-reflective properties. For conductor-backed structures, the suppression of parasitic modes represents the key issue.

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